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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

Lee CHEN, et al.

GROUP: 1763

SERIAL NO: 10/517,764

FILED: December 23, 2004

EXAMINER: OLSEN, ALLAN W

FOR: ANISOTROPIC DRY ETCHING OF CU-CONTAINING LAYERS

SUBMISSION OF SUPPLEMENTAL APPLICATION DATA SHEET

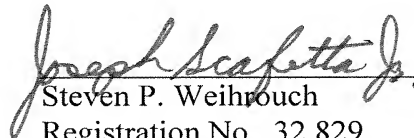
Office of Initial Patent Examination
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicant(s) submit herewith a Supplemental Application Data Sheet for the above-identified application for the purpose of correcting the 1st inventor's city of residence and his mailing address.

Respectfully Submitted,

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